

Lednium Release New LED Packages

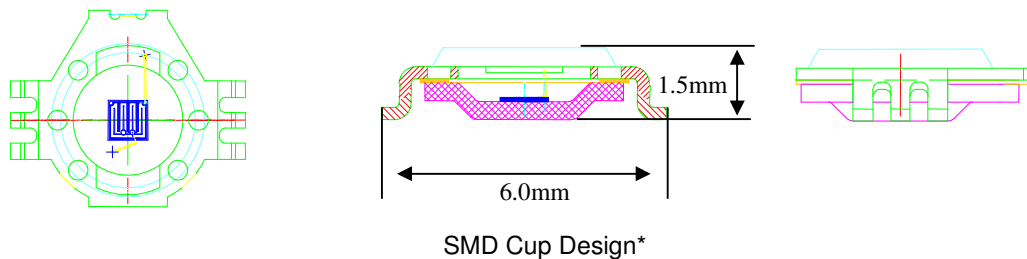
The surface mount device (SMD) cup and the next generation partial surface mount device (PSMD) cup will be formally released to the market in March 2007. These products are suitable for low profile high power LED applications, and come in a variety of colours and die sizes.

CUP SERIES PRODUCTS

SMD Cups

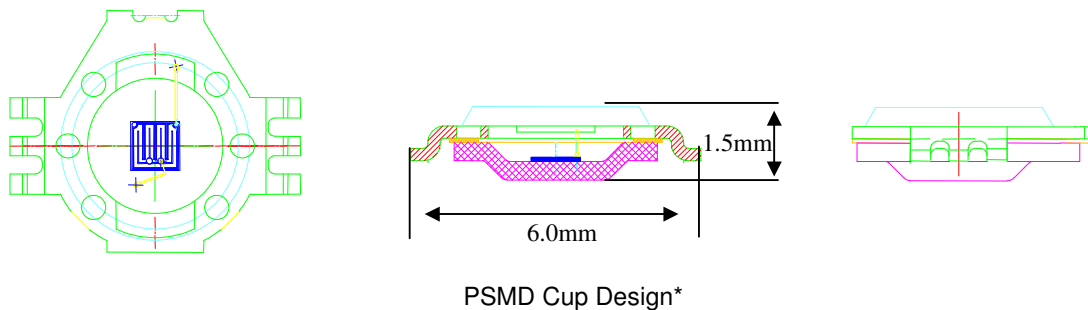
Market interest and feedback arising from the earlier release of the original PSMD range lead to the development of the SMD product. SMD cups are proving a popular configuration because of compatibility with the automatic board loading equipment in common use by assembly manufacturers.

Both PSMD and SMD LED cup products are available in red, amber, green, blue and white colours. White products are available in warm (CCT 3500K), daylight (CCT 5800K) and cool (CCT 7000K) colour temperature ranges.



PSMD Cups

This product was the first Lednium cup range to be released, and provides excellent thermal coupling and low profile board mounting. PSMD cups require the printed circuit boards on which they are mounted to be recessed with a hole, into which the product is inserted, resulting in the lowest profile of any large LED package on the market. The product requires less than 1.5mm of headroom above the mounting board. This design is ideal for the automotive, military, marine and commercial applications where low profile mounting is important.



TECHNICAL ADVANTAGES

Cup Series

Offers competitive advantages over other single die packages on the market:

- two mounting styles (PSMD and SMD)
- small PCB footprint
- lowest profile available for 1watt LEDs
- low thermal resistance of 2°C/watt
- compatibility of our packaging to SMT component placing systems
- the flexibility of three die ratings within a single product,
- available in 7 colours
- wide angle light dispersion (120°)
- alternate wavelength options (non-visible IR and UV devices)
- compatibility with optional secondary optics

* NB: Images may vary slightly to that shown at time of official release, please refer to data sheets for more detail.